

ABSTRACT

A resin composition for semiconductor encapsulation contains an epoxy resin (A); a phenolic compound (B) containing
 5 two or more phenolic hydroxyl groups; an inorganic filler (C); and a curing accelerator (D). The epoxy resin (A) contains an epoxy resin (a1) represented by the formula (1), and the resin composition has a moisture absorption rate of 0.22 weight % or less when the composition is humidified at 85°C
 10 and 85% R.H. for 168 hours:

